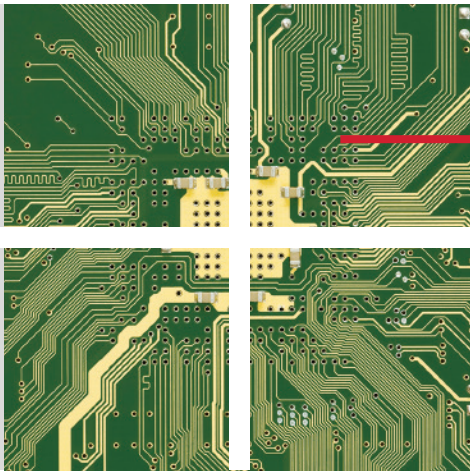


Affinity 2.0

Electroless Nickel / Immersion Gold



Prevent Aggressive Corrosion and Achieve the Highest Reliability.

Advanced technologies often bring increased complexity, but well-designed technologies bring performance AND simplicity. This is the benefit of **Affinity 2.0**, the highly stable, low corrosion electroless nickel immersion gold system from industry leader MacDermid Enthone. The best ENIG technologies, along with new innovations from three companies of plating experts, are now available as a unified plating system. Most importantly, Affinity 2.0 reduces process variation in all aspects of chemical control. Highly stable activation and nickel plating allows for an ultra-uniform gold deposition. The exceptional control provided increases reliability while reducing gold metal costs by 30% or more, all while reducing maintenance, labor and eliminating wasteful dummy plating.

MacDermid Enthone Electronics Solutions is a highly organized international supplier of chemical processes. Due to our global footprint, OEMs consider us a valuable partner in reducing variation within their electronics manufacturing supply chains. **Affinity 2.0** is the prime example of a process which can benefit OEMs whom demand high reliability/zero variation, as well as fabricators who are in business to produce a high-value circuit board.

KEY FEATURES

- Six-Sigma development and operation drives waste and defects out of the ENIG process
- Consistently low electroless nickel corrosion providing the highest level of conformance to IPC4552A specification
- Dummy free operation, eliminating waste material and time
- Significant gold distribution improvement over competitive ENIG systems, providing lowest process cost possible
- Consistent electroless nickel deposit phosphorous content over long solution life



MacDermid Enthone
ELECTRONICS SOLUTIONS

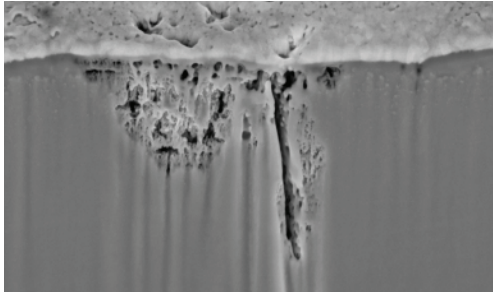
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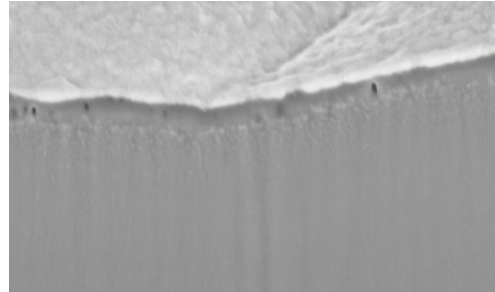


Other ENIGs Only Claim to Prevent Aggressive Nickel Corrosion. Affinity 2.0 Actually Does!

Each MacDermid Enthone Affinity ENIG 2.0 process step—from the pre-treatment and activation, to the simple-to-operate electroless nickel and low corrosion immersion gold—are formulated to work synergistically, providing a high reliability coating with simplified use. This unified approach ensures that the same high reliability ENIG finish is delivered, every single time.



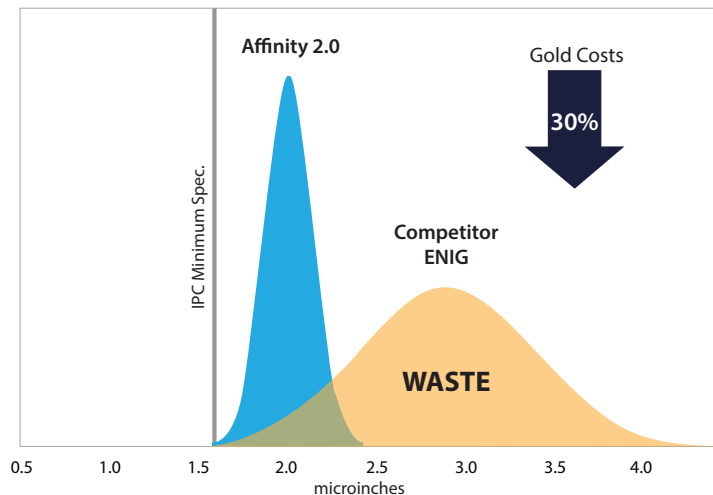
Traditional ENIG systems can show variation in electroless nickel deposit phosphorous composition, resulting in unwanted, localized, aggressive corrosion during plating.



Affinity 2.0 ENIG delivers a consistent 9% EN deposit over the solution life. This highly corrosion-resistant deposit, coupled with Affinity 2.0 Gold technology, provides low and consistent corrosion, eliminating unwanted, deep, localized corrosion.

Consistency Drives The Value

Affinity Gold Distribution vs. Competition



Consistent low corrosion observation, minimal gold usage and high performance and reliability make Affinity ENIG 2.0 the PCB Fabricators' choice for Electroless Nickel-Immersion Gold finishing. For more information, contact a MacDermid Enthone Electronics Solutions representative or visit AffinityENIG.com today.



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